

Abstract

Transparent pane with nontransparent contact surface  
for a connection by soldering

A transparent pane (1.1), in particular a glass pane, having at least one electroconducting, non-transparent contact surface (3) placed on one of its surfaces, in order to connect it by soldering to a connection piece (4). According to the invention in the region of the soldering location, the contact surface has at least one cutout (3A) via which the soldering filler metal (5) is visible through the pane (1.1) after the connection piece (4) has been soldered to the contact surface (3).

Such a configuration allows reliable visual verification of the soldering locations, even in cases in which the soldering location is incorporated within a composite glazing panel and has been soldered, if necessary by induction heating.

[Figure 2]